

L Number	Hits	Search Text	DB	Time stamp
-	56	semiconductor adj substrate and inductor and capacitor and radio adj frequency and etching and monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:36
-	130	(438/8).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:26
-	114	(438/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:28
-	259	radio adj frequency adj detection or radio adj frequency adj detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:30
-	17251	chemical adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:48
-	1	(radio adj frequency adj detection or radio adj frequency adj detector) and (chemical adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:33
-	141	lateral adj undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	15708	resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	110	(chemical adj etching) and resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	41	((chemical adj etching) and resonate) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:40
-	130	quartz adj crystal adj monitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:45
-	165128	receiver and transmitter	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46
-	185	(chemical adj etching) and (receiver and transmitter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46

-	2	5629244.URPN.	USPAT	2002/05/17 17:06
-	22	5639423.URPN.	USPAT	2002/05/17 17:10
-	30	("4219335" "4596697" "4598049" "4632808" "4673657" "4676274" "4683195" "4708931" "4737464" "4759828" "4908112" "4920056" "4952266" "4960486" "4963498" "5000817" "5003822" "5006749" "5129262" "5212988" "5220189" "5229297" "5252294" "5270183" "5296375" "5304487" "5385709" "5427946" "5486335" "5498392").PN.	USPAT	2002/05/17 17:12
-	5	5282921.URPN.	USPAT	2002/05/17 17:16
-	5	("2912497" "2967907" "3806643" "4423137" "4509162").PN.	USPAT	2002/05/17 17:17
-	256	(438/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:24
-	48	rf adj etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:41
-	5	5817573.URPN.	USPAT	2002/05/17 17:38
-	5	5817573.URPN.	USPAT	2002/05/17 17:38
-	14	("5141897" "5167760" "5231051" "5233223" "5254498" "5312773" "5326427" "5358621" "5364817" "5374849" "5387550" "5397742" "5407861" "5496773").PN.	USPAT	2002/05/17 17:38
-	1	"non-contact detection system" and (etch or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:43
-	435	high adj frequency adj detection or high adj frequency adj detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:44
-	330600	etch or etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	653629	silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	6	(high adj frequency adj detection or high adj frequency adj detector) and (etch or etching) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:45
-	0	chemical adj etching and (high adj frequency adj detection or high adj frequency adj detector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:48
-	1	"secondary ion emission spectroscopy"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:03

-	8	"leybold-inficon"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:04
-	405	radio adj waves and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:05
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:06
-	193	(radio adj waves and etching) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:42
-	0	(156/627.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:42
-	0	(156/627).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:46
-	2	("6210981").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:55
-	5	("5140164" "5629244" "5733820" "5821549" "5844416").PN.	USPAT	2002/05/19 11:46
-	18	("4639301" "4818872" "4843330" "4851097" "4875971" "4912327" "4924287" "4943769" "4954773" "4996659" "5057773" "5089774" "5140164" "5155368" "5376883" "5430305" "5521517" "5525806").PN.	USPAT	2002/05/19 11:47
-	5	5844416.URPN.	USPAT	2002/05/19 11:49
-	3	6210981.URPN.	USPAT	2002/05/19 11:50
-	9	("5127984" "RE34425" "5268065" "5413941" "5433650" "5433651" "5856871" "5891352" "6210981").PN.	USPAT	2002/05/19 11:52
-	0	6368881.URPN.	USPAT	2002/05/19 11:54
-	3	("5516339").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:56
-	2	5516339.URPN.	USPAT	2002/05/19 11:55
-	31	("4303748" "4547440" "4556614" "4589197" "4594299" "4631810" "4638407" "4654279" "4683181" "4722877" "4748542" "4758483" "4792504" "4818643" "4822701" "4830939" "4902589" "4908283" "4911995" "4925751" "4935317" "4997732" "5009970" "5011501" "5013619" "5037712" "5041346" "5089027" "5102752" "5176968" "5409786").PN.	USPAT	2002/05/19 11:55

-	1	"thickness detection" same radio	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:58
-	4	"thickness detection" same rf	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 11:58
-	14	"insitu" and etching and (rf or radio) and (monitoring or detection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:03
-	6	("4115184" "4207137" "4354154" "4963819" "5175472" "5273610").PN.	USPAT	2002/05/19 12:08
-	29	5467013.URPN.	USPAT	2002/05/19 12:09
-	144	"lateral undercut" or "lateral under-cut"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:33
-	5	(("6063642") or ("5559058")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:45
-	0	("physical adj measured and undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:45
-	0	("physical adj measured same undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	0	("physical adj measured same "undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	0	("undercut").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:46
-	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	1134671	measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	4169	undercut and measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	653629	silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47

-	1209	(undercut and measured) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:47
-	596606	lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	422	((undercut and measured) and silicon) and lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	1969	insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 12:48
-	1	((undercut and measured) and silicon) and lateral) and insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	3	("4763183" "5114233" "5539766").PN.	USPAT	2002/05/19 13:03
-	5	5739909.URPN.	USPAT	2002/05/19 13:04
-	252	(324/329).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	57	(324/341).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	264	(324/338).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:32
-	9	(324/364).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	301	(324/71.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:33
-	609	undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:34
-	88	silicon and (undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/19 13:34
-	2	5027064.URPN.	USPAT	2002/05/19 13:42
-	1926	sra or "surface resistance analyzer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:22

-	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:22
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	0	(sra or "surface resistance analyzer") and undercut and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	276	(sra or "surface resistance analyzer") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	128630	etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	4	((sra or "surface resistance analyzer") and semiconductor) and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
-	256	(438/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:08
-	70905	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:09
-	76	((438/381).CCLS.) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:31
-	17	((438/381).CCLS.) and inductor and polysilicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:32
-	961	(257/48).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
-	817207	coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
-	15	((257/48).CCLS.) and coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03
-	1481	lateral adj etch or lateral adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03

-	128	coil and (lateral adj etch or lateral adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:07
-	2082394	measure or measured or measuring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:08
-	81	(coil and (lateral adj etch or lateral adj etching)) and (measure or measured or measuring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:08
-	2	("5739909").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:24
-	11	5739909.URPN.	USPAT	2003/06/02 08:22
-	3	("4763183" "5114233" "5539766").PN.	USPAT	2003/06/02 08:23
-	182	scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:24
-	18	coil and scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:37
-	844792	monitor or monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:38
-	23	coil and (lateral adj etch or lateral adj etching) and (monitor or monitoring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:44
-	0	6340603.URPN.	USPAT	2003/06/02 08:41
-	10	("4522681" "4817815" "5007982" "5242536" "5877032" "5910011" "5926740" "6040248" "6121123" "6141183").PN.	USPAT	2003/06/02 08:41
-	0	6340603.URPN.	USPAT	2003/06/02 08:43
-	77609	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:45
-	5	(lateral adj etch or lateral adj etching) and (monitor or monitoring) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:46
-	1096	(438/14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:46
-	1	(lateral adj etch or lateral adj etching) and ((438/14).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:47